

Remarks

Claims 15, 17-19, and 21-25 were previously pending in the application. After entry of the response Claims 15, 17-19, and 21-25 will be pending. Reconsideration is respectfully requested based on the following remarks.

Claim Rejection 35 U.S.C. §102

Claims 15, 17, 19, 21, and 23-25 were rejected under 35 U.S.C. §102(e) as being anticipated by Ouchi et al. (U.S. Patent No. 6,320,691), herein referred to as “Ouchi”.

Of the above-referenced claims, Claims 15, 19, and 23 are independent. Accordingly, once allowability of these claims is established, all claims depending therefrom are likewise allowable.

Each of Claims 15, 19, and 23 generally recite that the spacing interval between the printed circuit board land groups is smaller than an interval between the tape carrier packages. Such pre-compression misalignment of the PCB and the TCP compensates for the expansion of the PCB such that respective PCB and TCP leads are substantially aligned during thermocompression bonding of the PCB and the TCP.

In contrast to Applicants’ claimed subject matter, Ouchi discloses no misalignment between the PCB and the TCP during any stage of the heat-pressure bonding process. In regard to Ouchi, the Examiner indicated that the TCPs are arranged at intervals of 0.3mm while the PCBs are arranged at intervals of 0.25mm (Office Action at the bottom of page 2 and the top of page 3). However, the actual **intervals** between TCPs and PCBs are not disclosed in Ouchi. More specifically, Applicants are unsure where the Examiner found the measurement of 0.3mm as it relates to the TCP as column 8, lines 35-51 reveals no such measurement.

Contrary to the Examiner's assertion, Ouchi does not "inherently use the pre-shrinking" PCB (Office Action at page 8). If Ouchi used a pre-shrunk PCB, Ouchi would not need to utilize a cooling means having a cooling nozzle 108. In this regard, Ouchi discloses, "After **alignment** of the input electrode pattern 106 with the corresponding connecting electrode pattern, these electrode patterns are heat-pressured bonded to each other by pressing the patterns against the PCB board 104 with the heat-pressure bonding head 115 while cooling the PCB board by cooling air blow supplied from the cooling nozzle 108" [emphasis added (column 10, lines 13-19)].

In further support for the alignment of the PCB and TCP, Ouchi discloses "a method of connecting first electrodes formed on a first substrate to second electrodes formed on a second substrate" including "**aligning the first electrodes with the second electrodes**" [emphasis added (Abstract)]. While column 9, lines 64-67 of Ouchi discloses, "an input electrode pattern 106 located **so as to be in alignment** with the connecting electrode pattern of the PCB board 104" (emphasis added).

Accordingly, Ouchi does not disclose, teach, or otherwise make obvious "respective second intervals between adjacent ones of the lands are smaller than the respective first intervals between adjacent ones of the corresponding tape carrier package leads" as recited in Claim 1, "tape carrier packages, each having a conductive lead group . . . spaced apart from adjacent lead groups at first intervals . . . a plurality of conductive land groups formed on the substrate . . . and spaced apart from each other at second intervals . . . wherein the second intervals are respectively smaller than the first intervals" as recited in Claim 19, and "forming printed circuit board land groups that correspond one-to-one with each of the tape

carrier packages on a substrate such that an interval between the printed circuit board land groups is smaller than an interval between the tape carrier packages” as recited in Claim 23.

For at least this reason, Applicants respectfully submit independent Claims 15, 19, and 23, and all claims depending therefrom are patentable.

Accordingly, Applicants respectfully request reconsideration and withdrawal of the rejections under 35 U.S.C. §102(e).

Claim Rejections 35 U.S.C. §103

Claims 15, 18, 19, 22, and 23 were rejected under 35 U.S.C. §103(a) as being unpatentable over the Conventional Art Admitted by Applicants in view of Ouchi.

Of the above-referenced claims, Claims 15, 19, and 23 are independent. Accordingly, once allowability of these claims is established, all claims depending therefrom are likewise allowable.

For at least the reasons cited above in regard to Ouchi, Applicants respectfully submit independent Claims 15, 19, and 23, and all claims depending therefrom are patentable.

Accordingly, Applicants respectfully request reconsideration and withdrawal of the rejections under 35 U.S.C. §103(a).

Conclusion

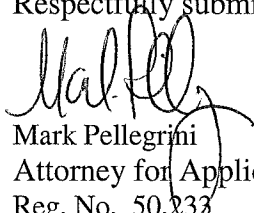
In view of the remarks set forth above, it is submitted that the application is now in condition for allowance. Authorization is given to charge any fees due or credit any overpayments in regard to this communication to deposit account 50-2257. If the Examiner has any questions or concerns, a telephone call to the undersigned at (949) 752-7040 is welcomed and encouraged.

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I hereby certify that this paper is being electronically transmitted to the U.S. Patent and Trademark Office on the date shown below.


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Respectfully submitted,


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